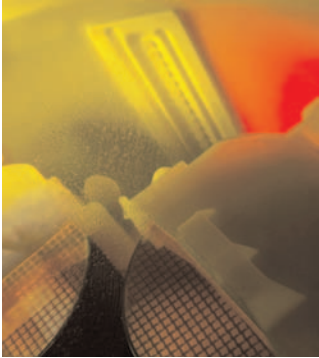




# Improvements in Photoresist Strip and Post-Ash Clean

High Performance and High Productivity for Advanced Needs

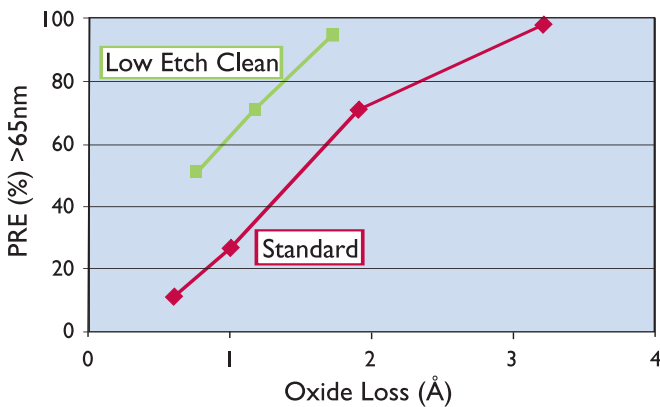


## LOW ETCH CLEAN

- Minimizes material loss AND increases particle removal efficiency
- Upgrade available on MERCURY® and ZETA® Systems.

## FLASHCLEAN™ ADVANTAGE

- Reduces defectivity at small particle sizes AND improves productivity.
- Upgrade available on ZETA Systems.

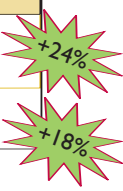


Low Etch Clean results are achieved by a new process incorporating dilute chemistries. System must be capable of dilute chemistry blending through low-flow pickup installation.

FlashClean™ Advantage improves defectivity through incorporation of new valves and control sequence that provide aspiration, purging the line of final rinse water.

Typical throughput on ZETA® 300 System

Applications	Standard	FlashClean™
Post-Ash Clean	130 wph	161 wph
Photoresist Strip	104 wph	123 wph



FSI International upgrade is inclusive of hardware, software and process support.

Contact us for a quote!

FlashClean Advantage improves productivity through new rotary union that enables hot water rinsing and optimized final dry.

FSI International, Inc.  
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